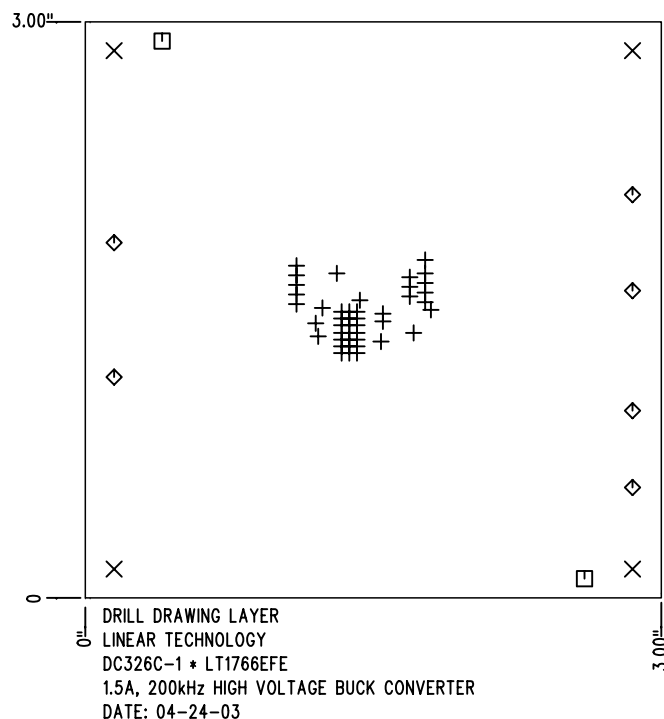


REVISIONS			
REV	DESCRIPTION	APPR	DATE
A	PROTOTYPE RELEASE		

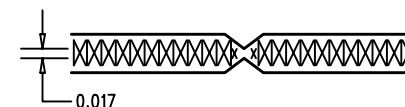


SHOWN FROM COMPONENT SIDE


SIZE	QTY	SYM	PLTD
0.01	44	+	PLTD
0.125	4	X	PLTD
0.07	2	□	NPLTD
0.094	6	◇	PLTD

#### NOTES : Unless Otherwise Specified

1. MATERIAL : FR4 OR EQUIVALENT EPOXY, 2 OZ. COPPER CLAD  
THICKNESS .062 +/- .006 TOTAL OF 4 LAYERS.
2. FINISH : ALL PLATED HOLES .001 MIN. / .0015 MAX. COPPER PLATE  
ELECTRODEPOSITED TIN-LEAD COMPOSITION  
BEFORE REFLOW , SOLDER MASK OVER BARE COPPER (SMOBC).
3. SOLDER MASK : BOTH SIDES USING LPI OR EQUIVALENT.
4. SILKSCREEN : USING WHITE NON-CONDUCTIVE EPOXY INK.
5. UNUSED SMD COMPONENTS SHOULD BE FREE OF SOLDER.
6. FILL UP ALL VIAS WITH SOLDER.
7. SCORING:



8. PLEASE LOOK AT THE README FILE FOR THE OTHER REQUIREMENTS.

APPROVALS			 <b>LINEAR TECHNOLOGY</b> 1630 McCarthy Blvd. Milpitas, CA 95035 PH: (408)432-1900	
	INIT	DATE		
DRAWN			<b>TITLE: FABRICATION DRAWING</b> <b>1.5A, 200kHz HIGH VOLTAGE BUCK CONVERTER</b>	
CHECK				
DESIGN	KIM T.	04-24-03		
ENGR	KEITH S.	04-24-03		
			SIZE	REV.
			A	A
SCALE = NONE			DES- 0000	SHT 1 of 1